





DETAIL G  
 VIEW ROTATED 90° CW

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TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 6 X 6 X 0.85, 32 I/O, 0.5 PITCH	DOCUMENT NO: 98ASA00395D	REV: A
	STANDARD: NON-JEDEC	
	SOT866-2	08 JAN 2016



NOTE:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING & TOLERANCING PER ASME Y14.5 – 2009.
3. THIS DIMENSION APPLIES TO METALIZED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL TIP.
4. BILATERAL COPLANARITY ZONE APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
5. THIS DIMENSION APPLIES ONLY FOR TERMINALS.
6. MOLD FLASH OR PLATING COVERAGE ON THE RING PAD AREA SHALL BE ALLOWABLE

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